PCN Number:			20	20130911001								PCN Date:		09/12/2013	
Title: Design revision for select LM3243TMx devices															
<b>Customer Contact:</b>			PCI	PCN Manager F				<b>ione:</b> +1(214)480-6037			-	<b>Dept:</b> Quality Service			
Proposed 1 <sup>st</sup> Ship Da			ıte:	te: 12/12/201			Λ.		Estimated			Sample	Date provided at		
Froposeu 1 Silip Da			12/12/201					Ava			ilability:	lability: sample request			
Cha	<b>Change Type:</b>														
		embly Site		Assembly			•				Assembly Materials				
	Des						•	Specification			Mechanical Specification				
Н		t Site						pping/Labeling			Test Process				
					mp Material			Wafer Bump Process							
☐ Wafer Fab Site				누	Wafer Fab Materials						Wafer Fab Process				
				☐ Part number change											
PCN Details															
Des	scrip	tion of Chang	je:												
guaranteed datasheet specifications or electrical performance. This change is only intended to improve the device's manufacturability.  The table below describes changes that were made:  Description of Change  Minor layout changes are being made to the LM3243TM to improve the accuracy of parametric trim at final test. Does not change the device's															
the parametric trim at final test. guaranteed electrical performance.  There is no datasheet change required.  Reason for Change:															
														<u> </u>	
Address parametric shifts due to post bump assembly stress that is presently being sub- optimally trimmed at final test. This change will improve the accuracy of the parametric trim and the overall manufacturability of the device.															
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):															
None															
Changes to product identification resulting from this PCN:															
Nor	ne	•													
		Affected:													
			_			204071:-	/NIOF		11100.10	_				2710//1/2055	
LM3243TME					LM3243TME/NOPB				LM3243TMX				M324	3TMX/NOPB	

Qualification Plan:								
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.								
Qual Vehicle 1: LM3243TMX/NOPB								
Package/Die Construction Details								
Assembly Site:	TIEM-N	1ELAKA	# Pins-Designator, Family:	16-PWF	P, YQF			
Fab Process:	MFAB		Package Type:					
Qualification:	Plan	☐ Test F	Results					
Reliability Test		Conditions	s	Sample Size (PASS/FAIL)				
High Temp Operating	Life	125C (16	8, 500, 1000 Hrs)	77/0				
ESD CDM		+/- 250V,	, 500V, 750V,1000V, 1500V	3/0				
ESD HBM		+/- 500V,	, 1000V, 1500V, 2000V, 2500	3/0				
Latch-up		(per JESD	78) 125C	6/0				
Latch-up		(per JESD	978) 25C	6/0				
Latch-up		(per JESD	78) 85C	6/0				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com